



## PMP11047 REV A Bill of Materials

1 C1, C2, C3 3 2.2uF GRM32ER72A225KA35L MuRata CAP, CERM, 2.2 μF.	100 V. +/- 10%, X7R, 1210 1210
	100 v, 1/- 10/0, XIX, 1210
2 C4 1 1uF GRM188R61E105KA12D MuRata CAP, CERM, 1 μF, 2	5 V, +/- 10%, X5R, 0603 0603
3 C5 1 220uF EKZE350ETD221MJC5S Nippon Chemi-Con CAP, AL, 220 μF, 35	V, +/- 20%, 0.053 ohm, TH TH, 2-Leads, Body
	10x12.5mm, Pin
	Spacing 5mm
4 C6, C8 2 10uF GRM32ER71H106KA12L MuRata CAP, CERM, 10 µF,	50 V, +/- 10%, X7R, 1210 1210
5 C7 1 330pF GRM188R72E331KW07D MuRata CAP, CERM, 330 pF	250 V, +/- 10%, X7R, 0603 0603
6 C9 1 100pF GRM1885C1H101JA01D MuRata CAP, CERM, 100 pF	50 V, +/- 5%, C0G/NP0, 0603 0603
7 C11, C15 2 1uF GRM21BR71H105KA12L MuRata CAP, CERM, 1 μF, 5	0 V, +/- 10%, X7R, 0805 0805
8 C12 1 1000pF VY2102M29Y5UG63V7 Vishay-Bccomponents CAP, CERM, 1000pF	, 300V, +/-20%, Y5U, Radial Disc 7.5mm, Is=7.5 Radial Disc 7.5mm,
	ls=7.5
9 C14 1 0.1uF C0603C104J3RAC Kemet CAP, CERM, 0.1 µF.	25 V, +/- 5%, X7R, 0603 0603
10 C27 1 0.047uF GRM188R71H473KA61D MuRata CAP, CERM, 0.047 J	F, 50 V, +/- 10%, X7R, 0603 0603
11 C100 1 1000pF GRM188R71E102KA01D MuRata CAP, CERM, 1000 p	=, 25 V, +/- 10%, X7R, 0603 0603
12 D1 1 150V PDS4150-13 Diodes Inc. Diode, Schottky, 150	V, 4 A, PowerDI5 PowerDI5
13 D2 1 24V SMAJ24CA Littelfuse Diode, TVS, Bi, 24 V	
14 D3 1 200V ES1D-13-F Diodes Inc. Diode, Ultrafast, 200	V, 1 A, SMA SMA
15 D10, D11 2 1.4V BAS316,115 NXP Semiconductor Diode, Ultrafast, 100	/, 0.25A, SOD-323 SOD-323
	5.5mm Pitch, 2-Pos, TH 7.0x8.2x6.5mm
	@ 100MHz, 6A, 1206 1206
Products	
18 Q1 1 100V CSD19534Q5A Texas Instruments MOSFET, N-CH, 100	V, 10 A, SON 5x6mm SON 5x6mm
19 R1 1 499k CRCW0603499KFKEA Vishay-Dale RES, 499 k, 1%, 0.1	
20 R2 1 10 CRCW120610R0JNEA Vishay-Dale RES, 10, 5%, 0.25 V	
21 R3, R13 2 0 CRCW06030000Z0EA Vishay-Dale RES, 0, 5%, 0.1 W,	0603 0603
22 R4 1 100 CRCW1206100RJNEA Vishay-Dale RES, 100, 5%, 0.25	N, 1206 1206
23 R5 1 37.4k CRCW060337K4FKEA Vishay-Dale RES, 37.4 k, 1%, 0.	W, 0603 0603
24 R6, R15 2 1.00k CRCW06031K00FKEA Vishay-Dale RES, 1.00 k, 1%, 0.	W, 0603 0603
25 R7 1 130k CRCW0603130KFKEA Vishay-Dale RES, 130 k, 1%, 0.1	W, 0603 0603
26 R8 1 0.1 CRA2512-FZ-R100ELF Bourns RES, 0.1, 1%, 3 W,	2512 2512
27 R9 1 1.00k CRCW08051K00FKEA Vishay-Dale RES, 1.00 k, 1%, 0.	25 W, 0805 0805
28 R14 1 10.0k CRCW060310K0FKEA Vishay-Dale RES, 10.0 k, 1%, 0.	W, 0603 0603
29 R28 1 100k CRCW0603100KFKEA Vishay-Dale RES, 100 k, 1%, 0.1	
30 R29 1 1.15k CRCW06031K15FKEA Vishay-Dale RES, 1.15 k, 1%, 0.	W, 0603 0603
31 R100, R101 2 0 CRCW12060000Z0EA Vishay-Dale RES, 0, 5%, 0.25 W	1206 1206
32 T1 1 60 uH 750315252 Wurth Elektronik eiSos Transformer, 60 uH,	H 21.08x21.08mm
33 TP3, TP5 2 Red 5010 Keystone Test Point, Multipurp	ose, Red, TH Red Multipurpose
	Testpoint
34 TP4, TP6 2 Black 5011 Keystone Test Point, Multipurp	ose, Black, TH Black Multipurpose
	Testpoint
35 U1 1 LM5022MM Texas Instruments 60V Low Side Contro	ller for Boost and SEPIC, 10-pin MSOP MUB10A
	Shunt Regulator, 34 ppm / degC, 100 mA, -40 to DBZ0003A
	3 (DBZ), Green (RoHS & no Sb/Br)
	ansitor, 80-160%, SSOP-4 7x2.12x2.6mm

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